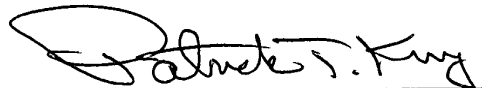


If a telephone call would expedite prosecution or handling of the present Application, the Applicant's attorney would appreciate a telephone call.

Respectfully submitted,

LAW OFFICES OF PATRICK T. KING

Date: July 16, 2003



Patrick T. King
Reg. No. 28,231
144 Holm Road #39
Watsonville, CA 95076-2427
Phone: (831) 722-8591
Facsimile: (831) 722-8591

Appendix A - Marked up Amended Claims

Serial No.: 10/014,928

43. (Amended) A method of operating a dual-die, double-sized, back-to-back integrated-circuit chip assembly, comprising the steps of:

mounting a pair of integrated-circuit chips back-to-back, where each integrated-circuit chip has one or more pairs of reversible wire-bonding pads; and

electrically reversing internal connections to the wire-bonding-pads on one of the integrated-circuit chips so that pads on each integrated-circuit chip for similar functions are located near each other for wire-bonding so that identical integrated-circuit chips are used to provide the dual-die, double-sized, back-to-back integrated-circuit chip assembly;

applying an external voltage to a bonding-option wire-bonding-pad to indicate whether the integrated-circuit chip is to provide a standard pattern for the reversible wire-bonding-pads, or alternatively, whether the integrated-circuit chip is to provide a reversed path for the reversible wire-bonding-pads; and

sensing the voltage applied to the bonding-option wire-bonding-pad for alternatively generating either a standard NRO gate control signal or a non-standard, reversed RO gate control signal from the voltage state of the bonding-option wire-bonding-pad.